

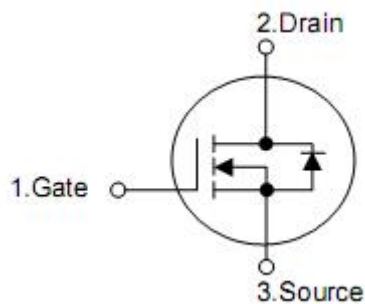
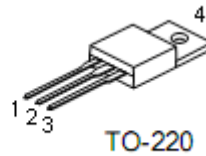
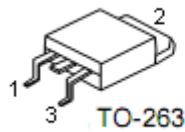
1. Applications

- n DC-DC converters and Off-line UPS

2. Features

- n $R_{DS(on)} = 3.0m\Omega @ V_{GS} = 10 V$
- n Super high dense cell design
- n Ultra low On-Resistance
- n Fast recovery body diode
- n Lead Free and Green devices available (RoHS Compliant)

3. Pin configuration



Pin	Function
1	Gate
2	Drain
3	Source
4	Drain

4. Absolute maximum ratings

($T_C=25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Units
Drain-source voltage		V_{DSS}	40	V
Gate-source voltage		V_{GSS}	± 20	V
Continuous drain current $T_C=25\text{ }^\circ\text{C}^1$		I_D	150	A
Continuous drain current $T_C=100\text{ }^\circ\text{C}$			108	A
300us pulsed drain current tested $T_C=25\text{ }^\circ\text{C}^2$		I_{DP}	600	A
Avalanche energy single pulse ³		E_{AS}	400	mJ
Power dissipation	$T_C=25\text{ }^\circ\text{C}$	P_D	188	W
	$T_C=100\text{ }^\circ\text{C}$		94	W
Maximum junction temperature		T_J	175	$^\circ\text{C}$
Storage temperature range		T_{STG}	-55~+175	$^\circ\text{C}$
Diode continuous forward current $T_C=25\text{ }^\circ\text{C}^1$		I_S	150	A

5. Thermal characteristics

Parameter	Symbol	Rating	Unit
Thermal resistance, Junction-to-case	θ_{JC}	0.8	$^\circ\text{C/W}$

6. Electrical characteristics

(T_C=25°C, unless otherwise notes)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	40	-	-	V
Drain-to-source leakage current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	μA
		T _J =85 °C	-	-	30	μA
Gate-to-source leakage current	I _{GSS}	V _{GS} =20V, V _{DS} =0V	-	-	100	nA
		V _{GS} =-20V, V _{DS} =0V	-	-	-100	nA
On characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	3.0	4.0	V
Static drain-source on-resistance ⁴	R _{DS(on)}	V _{GS} =10V, I _D =75A	-	3.0	4.0	mΩ
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} =20V, V _{GS} =0V, f=1.0MHz	-	3870	-	pF
Output capacitance	C _{oss}		-	680	-	
Reverse transfer capacitance	C _{rss}		-	363	-	
Gate series resistance	R _G	V _{DS} =0V, V _{GS} =0V, f=1.0MHz	-	1.8	-	Ω
Total gate charge	Q _g	V _{DD} =32V, I _D =75A, V _{GS} =10V	-	95	-	nC
Gate-source charge	Q _{gs}		-	20	-	
Gate-drain (Miller) charge	Q _{gd}		-	30	-	
Resistive switching characteristics						
Turn-on delay time	T _{d(ON)}	V _{DD} =20V, I _D =75A, V _{GS} =10V, R _G =4.7Ω	-	35	-	nS
Rise time	t _{rise}		-	106	-	
Turn-off delay time	T _{d(OFF)}		-	84	-	
Fall time	t _{fall}		-	46	-	
Source-drain body diode characteristics T_J=25°C, unless otherwise notes						
Diode forward voltage ⁴	V _{SD}	V _{GS} =0V, I _S =75A	-	-	1.2	V
Reverse recovery time	t _{rr}	I _{SD} =75A, di _F /dt=100A/μs,	-	45	-	ns
Reverse recovery charge	Q _{rr}		-	90	-	nC

Note: 1. Calculated continuous current based on maximum allowable junction temperature. Limited by bonding wire.

2. Pulse width limited by safe operating area.

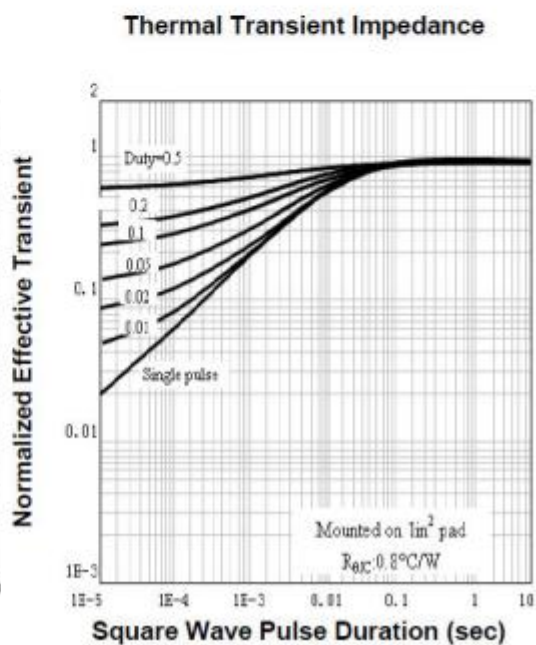
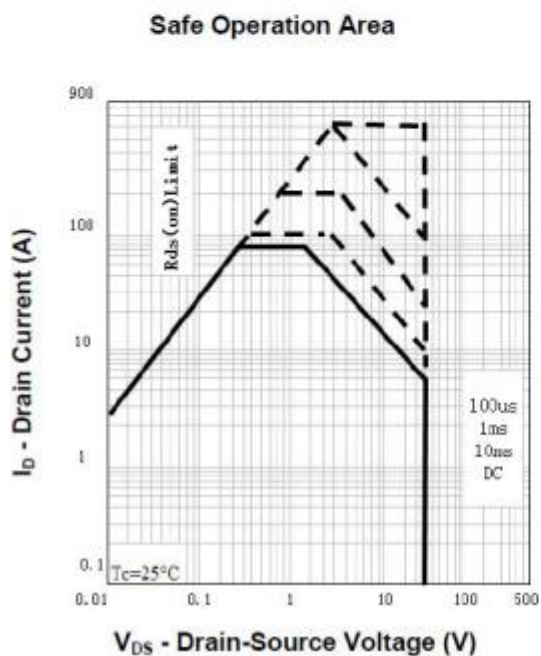
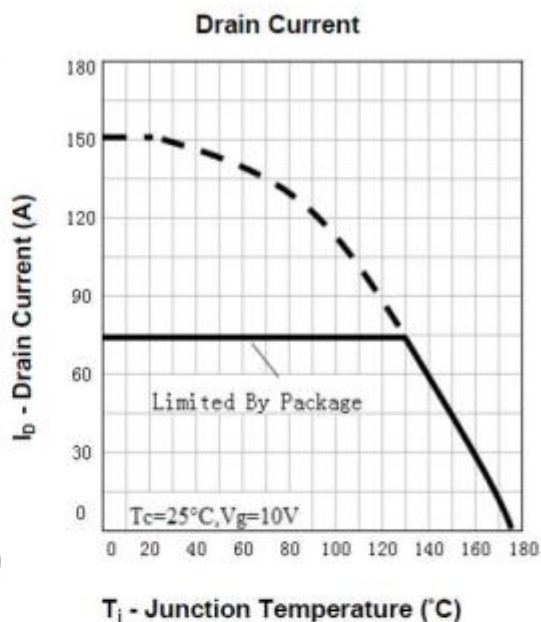
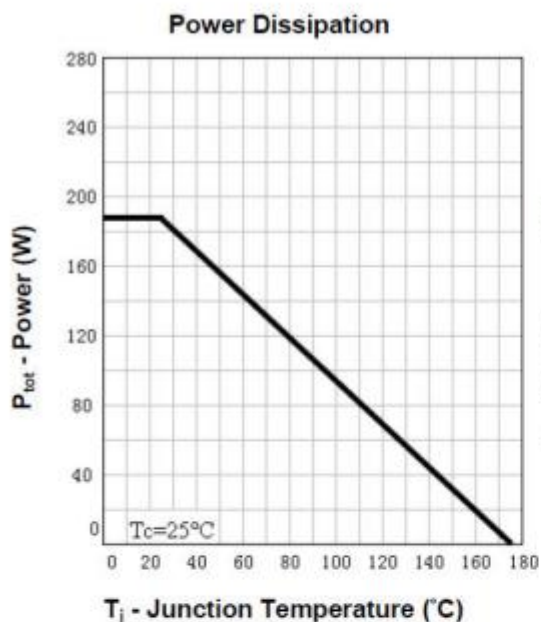
3. Limited by T_{Jmax}, I_{AS}=40A, V_{DD}=32V, R_G=47Ω, Starting T_J=25°C.

4. Pulse test; Pulse width ≤300μs; duty cycle ≤2%.

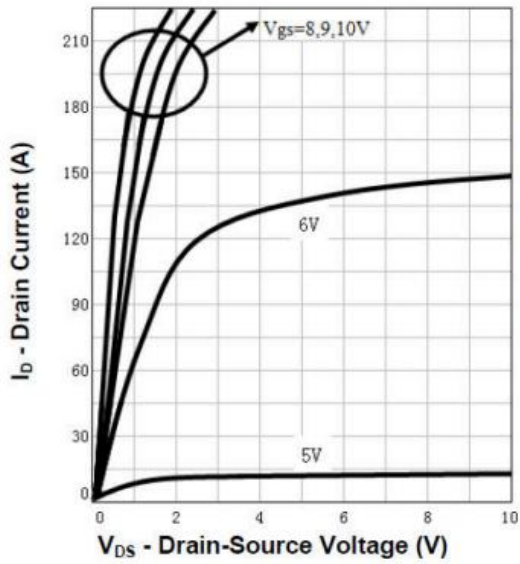
5. Guaranteed by design, not subject to production testing.

6. KIA finished product specifications please customer before placing order, should obtain the latest version of the finished product specifications.

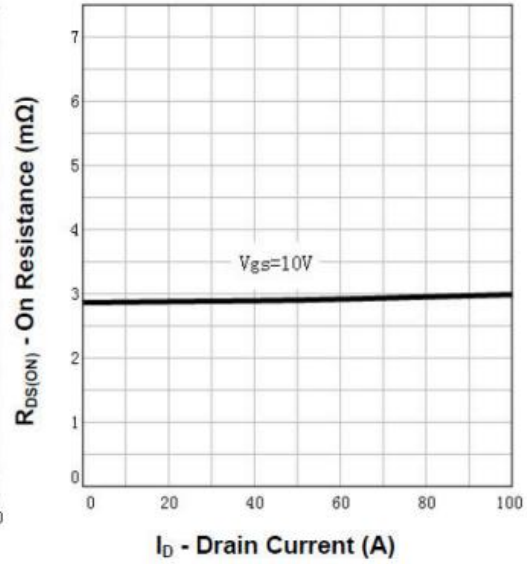
7. Typical characteristics



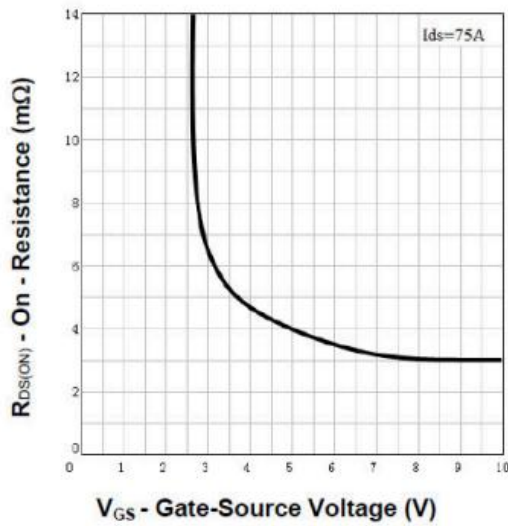
Output Characteristics



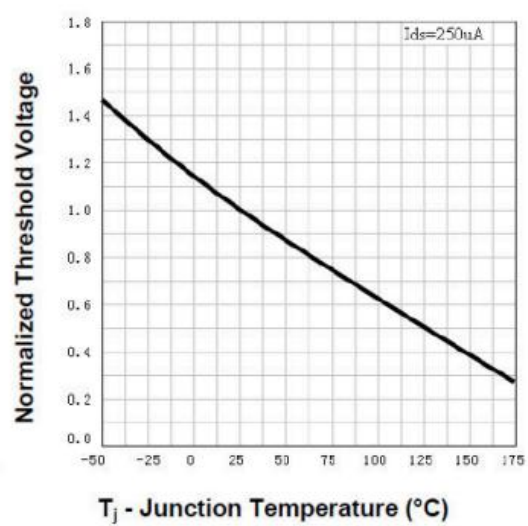
Drain-Source On Resistance



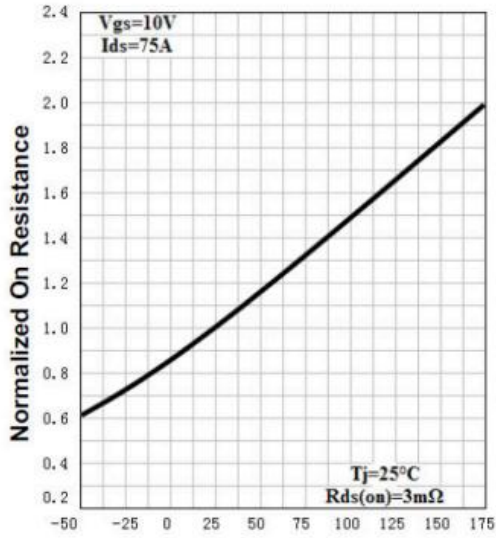
Drain-Source On Resistance



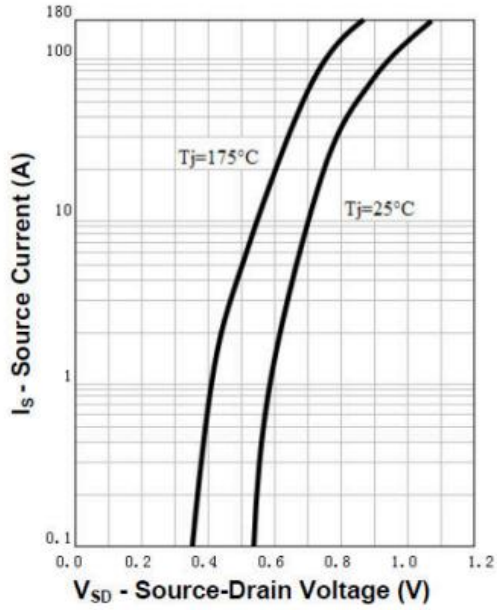
Gate Threshold Voltage



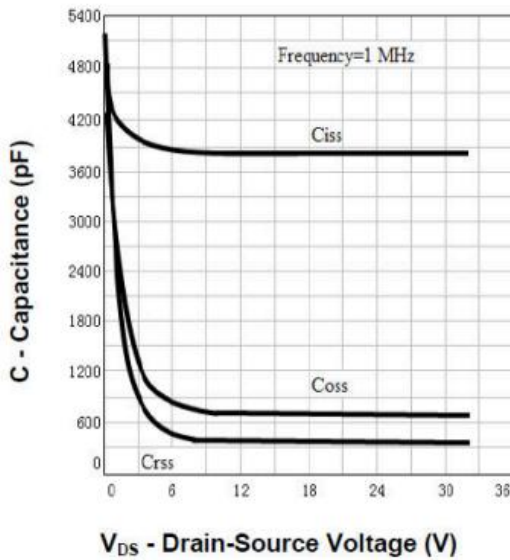
Drain-Source On Resistance



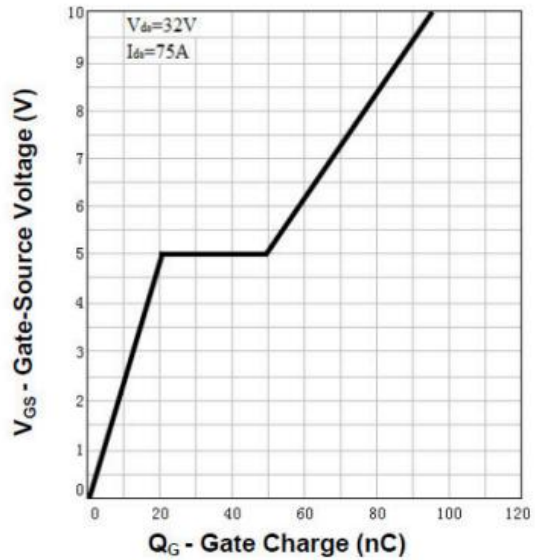
Source-Drain Diode Forward



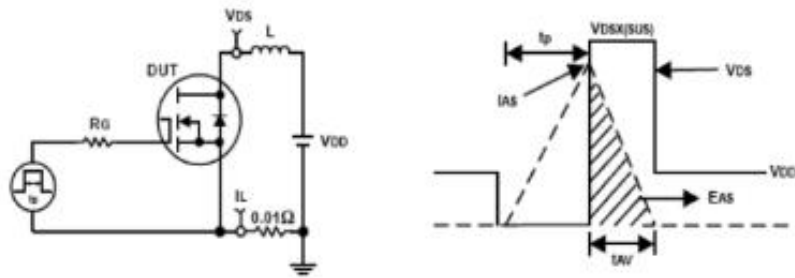
Capacitance



Gate Charge



8. Test circuits and waveforms



Switching Time Test Circuit and Waveforms

